

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jennifer Y. SUN	01/05/2010
Senh THACH	12/18/2009
Ren-Guan DUAN	01/04/2010
RECEIVING PARTY DATA	
Name:	Applied Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12640496
CORRESPONDENCE DATA	
Fax Number:	(408)986-3090
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	408-563-5758
Email:	pauline_fischer@amat.com
Correspondent Name:	Pauline S. Fischer
Address Line 1:	Applied Materials, Inc.
Address Line 2:	P.O. Box 450 A
Address Line 4:	Santa Clara, CALIFORNIA 95052
ATTORNEY DOCKET NUMBER:	14147US/ETCH/CHMBR/MDD
NAME OF SUBMITTER:	Pauline Fischer

Total Attachments: 4
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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Name and Address
of Inventors:

1) **JENNIFER Y. SUN**
106 ~~1056~~ Oak Haven Place
Mountain View, CA 94041

3) **REN-GUAN DUAN**
3645 Independence Road
Fremont, CA 94538

2) **SENH THACH**
32257 Jean Drive
Union City, CA 94587

(hereinafter referred to as Assignors), have invented a certain invention entitled:

HIGH TEMPERATURE ELECTROSTATIC CHUCK BONDING ADHESIVE

for which we have filed an application for a Patent of the United States on December 17, 2009
Serial No. 12/640,496; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon,

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PATENT


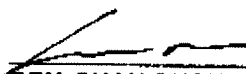
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including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignor in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- 1) 01/05 ²⁰¹⁰ ~~2009~~  _____
JENNIFER Y. SUN
- 2) _____ 2009 _____
SENH THACH
- 3) 01/04 ²⁰⁰⁹ ~~2010~~ ^(RGD)  _____
REN-GUAN DUAN

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Name and Address
of Inventors:

- | | |
|--|--|
| 1) JENNIFER Y. SUN
1056 Oak Haven Place
Mountain View, CA 94041 | 3) REN-GUAN DUAN
3645 Independence Road
Fremont, CA 94538 |
| 2) SENH THACH
32257 Jean Drive
Union City, CA 94587 | |

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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____, 2009

JENNIFER Y. SUN

2) Dec 18, 2009



SENH THACH

3) _____, 2009

REN-GUAN DUAN